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Kind regards,

Team Nexperia

PSMN1R2-25YL

N-channel 25 V 1.2 mΩ logic level MOSFET in LFPAK

Rev. 01 — 25 June 2009 Product data sheet

1. Product profile

1.1 General description

Logic level N-channel MOSFET in LFPAK package qualified to 150 °C. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

1.2 Features and benefits

- Advanced TrenchMOS provides low RDSon and low gate charge
- High efficiency gains in switching power converters
- Improved mechanical and thermal characteristics
- LFPAK provides maximum power density in a Power SO8 package

1.3 Applications

- DC-to-DC converters
- Lithium-ion battery protection
- Load switching
- Motor control
- Server power supplies

1.4 Quick reference data

Table 1. Quick reference

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C		-	-	25	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 10 V; see Figure 1	[1]	-	-	100	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2		-	-	121	W
T_j	junction temperature			-55	-	150	°C
Avalanche ruggedness							
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; I_D = 100 A; $V_{sup} \leq 25$ V; R_{GS} = 50 Ω; unclamped		-	-	677	mJ
Dynamic characteristics							
Q_{GD}	gate-drain charge	V_{GS} = 4.5 V; I_D = 25 A; V_{DS} = 12 V; see Figure 12; see Figure 13		-	11.9	-	nC
$Q_{G(tot)}$	total gate charge			-	50.6	-	nC

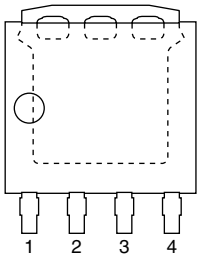
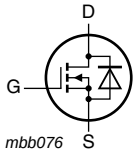
Table 1. Quick reference *…continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 15 A; T_j = 100 °C; see Figure 11	-	-	1.6	mΩ
		V_{GS} = 10 V; I_D = 15 A; T_j = 25 °C; see Figure 10	-	0.9	1.2	mΩ

[1] Continuous current is limited by package.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 SOT1023 (LFPAK2)	
2	S	source		
3	S	source		
4	G	gate		
mb	D	drain		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN1R2-25YL	LFPAK2	Plastic single-ende surface-mounted package (LFPAK2); 4 leads	SOT1023

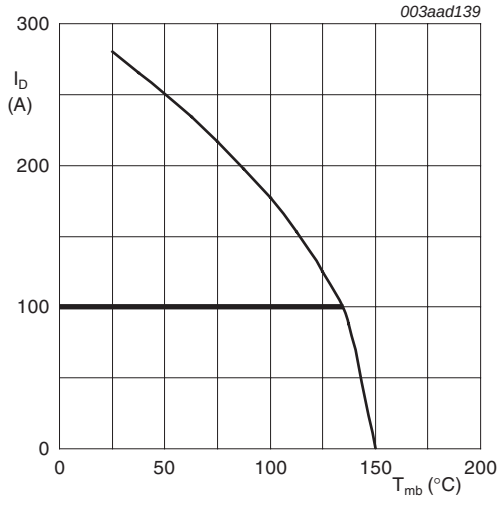
4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

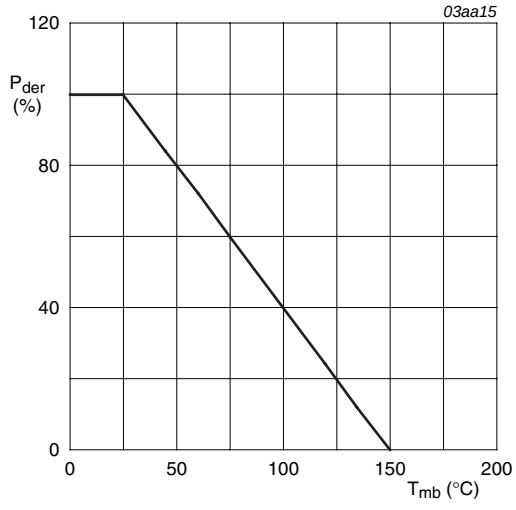
Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C		-	25	V
V_{DGR}	drain-gate voltage	$T_j \geq 25$ °C; $T_j \leq 150$ °C; R_{GS} = 20 kΩ		-	25	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	V_{GS} = 10 V; T_{mb} = 100 °C; see Figure 1	[1]	-	100	A
		V_{GS} = 10 V; T_{mb} = 25 °C; see Figure 1	[1]	-	100	A
I_{DM}	peak drain current	$t_p \leq 10$ µs; pulsed; T_{mb} = 25 °C; see Figure 3		-	815	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; see Figure 2		-	121	W
T_{stg}	storage temperature			-55	150	°C
T_j	junction temperature			-55	150	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C
Source-drain diode						
I_S	source current	T_{mb} = 25 °C;	[1]	-	100	A
I_{SM}	peak source current	$t_p \leq 10$ µs; pulsed; T_{mb} = 25 °C		-	815	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; I_D = 100 A; $V_{sup} \leq 25$ V; R_{GS} = 50 Ω; unclamped		-	677	mJ

[1] Continuous current is limited by package.



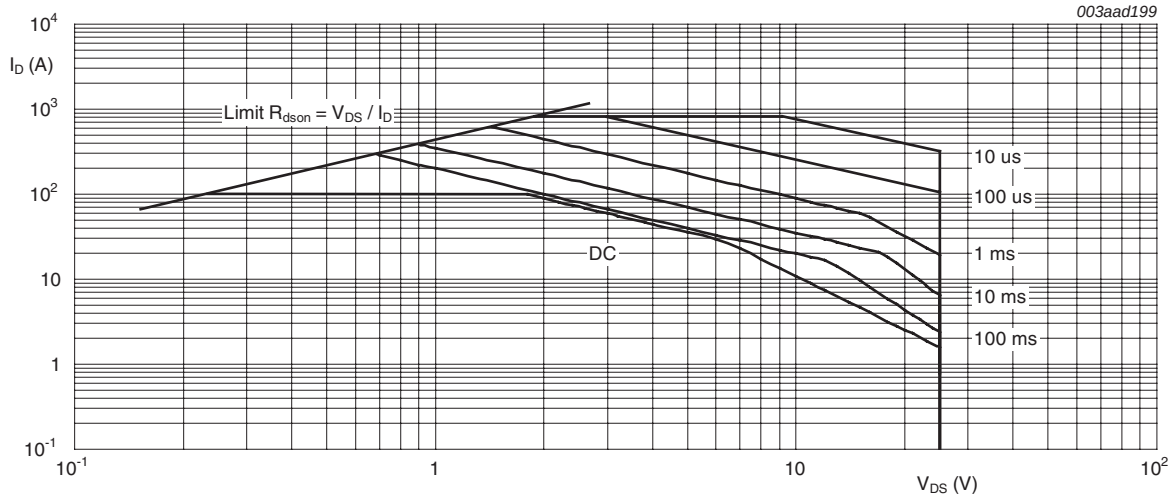
$V_{GS} \geq 5V(1)$ Capped at 100A due to package

Fig 1. Continuous drain current as a function of mounting base temperature



$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

Fig 2. Normalized total power dissipation as a function of mounting base temperature



$T_{sp} = 25\,°C; I_{DM}$ is single pulseCapped at 100A due to package

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	0.4	1	K/W

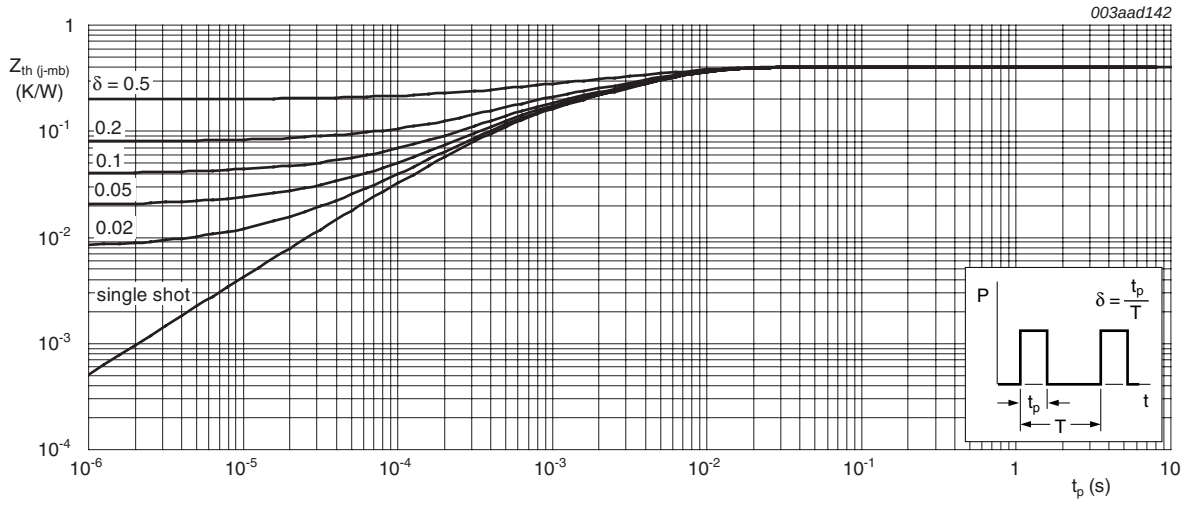


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

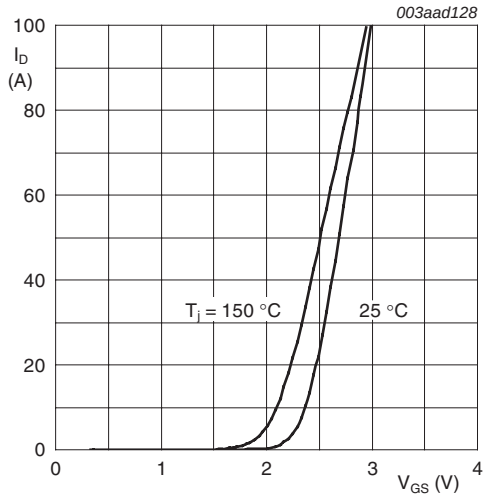
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 250 µA; V_{GS} = 0 V; T_j = 25 °C	25	-	-	V
		I_D = 250 µA; V_{GS} = 0 V; T_j = -55 °C	22	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; see Figure 8; see Figure 9	1.3	1.7	2.15	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 150 °C; see Figure 9	0.65	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; see Figure 9	-	-	2.45	V
I_{DSS}	drain leakage current	V_{DS} = 25 V; V_{GS} = 0 V; T_j = 25 °C	-	-	1.5	µA
		V_{DS} = 25 V; V_{GS} = 0 V; T_j = 150 °C	-	-	500	µA
I_{GSS}	gate leakage current	V_{GS} = 16 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
		V_{GS} = -16 V; V_{DS} = 0 V; T_j = 25 °C	-	-	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 4.5 V; I_D = 15 A; T_j = 25 °C; see Figure 10	-	1.2	1.85	mΩ
		V_{GS} = 10 V; I_D = 15 A; T_j = 100 °C; see Figure 11	-	-	1.6	mΩ
		V_{GS} = 10 V; I_D = 15 A; T_j = 150 °C; see Figure 11	-	-	2.1	mΩ
		V_{GS} = 10 V; I_D = 15 A; T_j = 25 °C; see Figure 10	-	0.9	1.2	mΩ
R_G	gate resistance	f = 1 MHz	-	0.94	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DS} = 12 V; V_{GS} = 10 V; see Figure 12; see Figure 13	-	105	-	nC
		I_D = 25 A; V_{DS} = 12 V; V_{GS} = 4.5 V; see Figure 12; see Figure 13	-	50.6	-	nC
Q_{GS}	gate-source charge	I_D = 25 A; V_{DS} = 12 V; V_{GS} = 4.5 V; see Figure 12; see Figure 13	-	19.3	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	8.1	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	4.5	-	nC
Q_{GD}	gate-drain charge		-	11.9	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	V_{DS} = 12 V; see Figure 12	-	2.6	-	V
C_{iss}	input capacitance	V_{DS} = 12 V; V_{GS} = 0 V; f = 1 MHz; T_j = 25 °C; see Figure 14	-	6380	-	pF
C_{oss}	output capacitance		-	1640	-	pF
C_{rss}	reverse transfer capacitance		-	644	-	pF

Table 6. Characteristics *…continued*

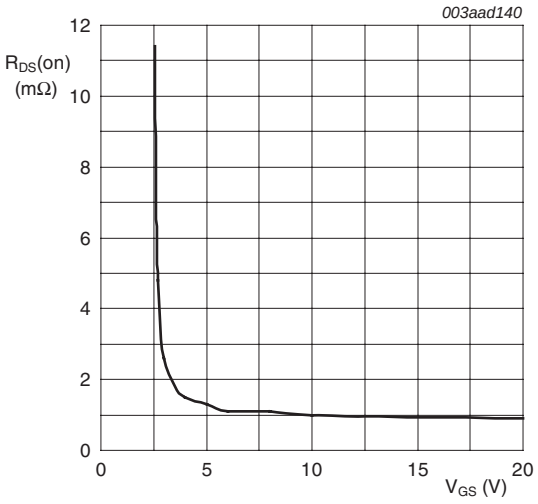
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$t_{d(on)}$	turn-on delay time	V_{DS} = 12 V; R_L = 0.5 Ω; V_{GS} = 4.5 V; $R_{G(ext)}$ = 5.6 Ω	-	69	-	ns
t_r	rise time		-	125	-	ns
$t_{d(off)}$	turn-off delay time		-	94	-	ns
t_f	fall time		-	56	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 25 A; V_{GS} = 0 V; T_j = 25 °C; see Figure 15	-	0.78	1.2	V
t_{rr}	reverse recovery time	I_S = 20 A; dI_S/dt = -100 A/µs; V_{GS} = 0 V; V_{DS} = 20 V	-	52	-	ns
Q_r	recovered charge		-	66	-	nC

[1] Tested to JEDEC standards where applicable.



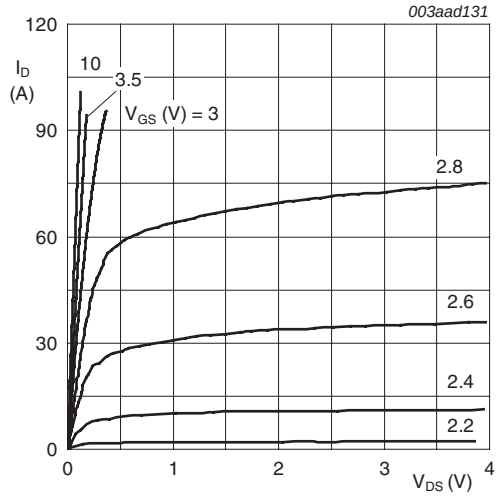
$V_{DS} = 10V$

Fig 5. Transfer characteristics: drain current as a function of gate-source voltage; typical values



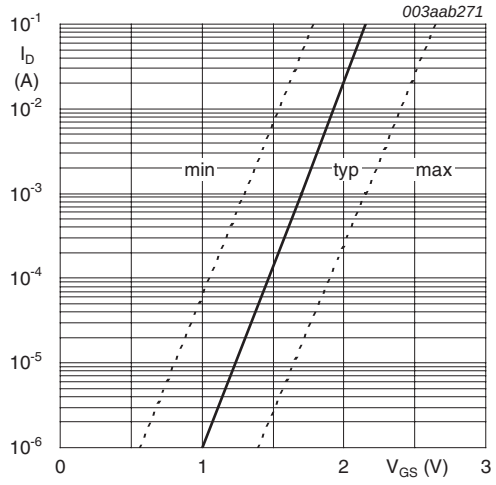
$T_j = 25\,°C; I_D = 15A$

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



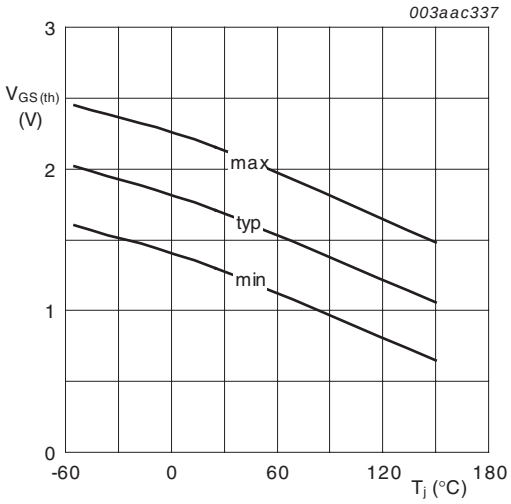
$T_j = 25\,°C;\ t_p = 300\,\mu s$

Fig 7. Output characteristics: drain current as a function of drain-source voltage; typical values



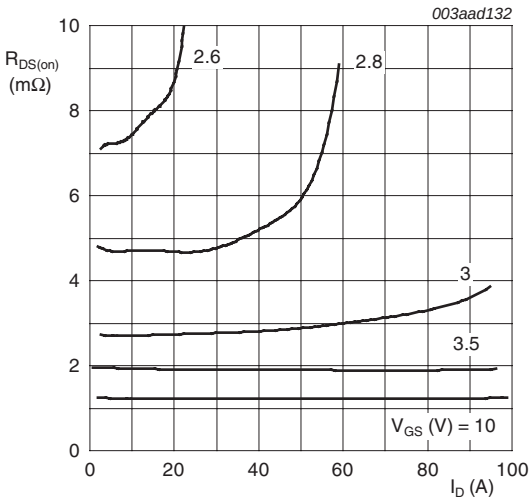
$T_j = 25\,°C; V_{DS} = 5\,V$

Fig 8. Sub-threshold drain current as a function of gate-source voltage



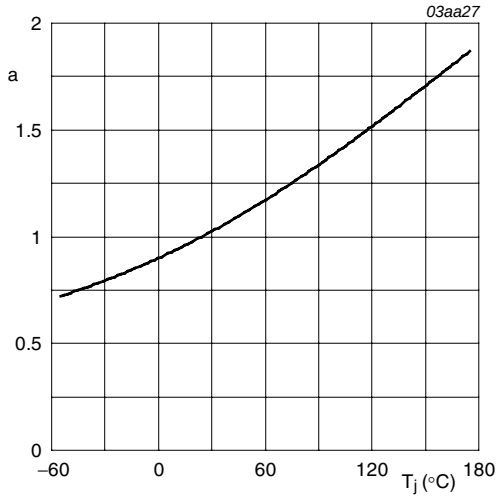
$I_D = 1\,mA; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature



$T_j = 25\,°C;\ t_p = 300\,\mu s$

Fig 10. Drain-source on-state resistance as a function of drain current; typical values



$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

Fig 11. Normalized drain-source on-state resistance factor as a function of junction temperature

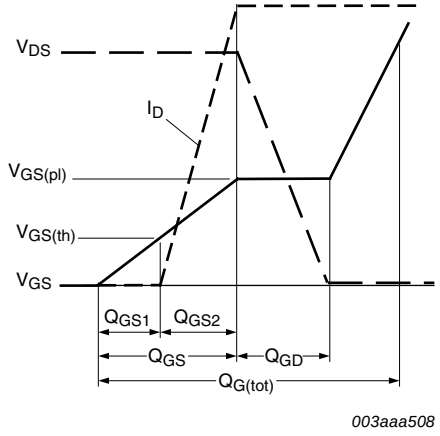
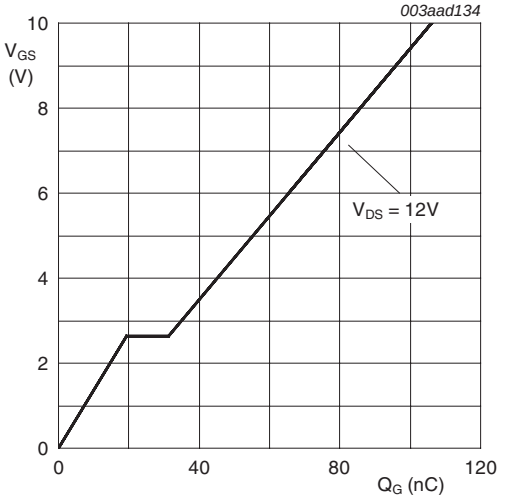
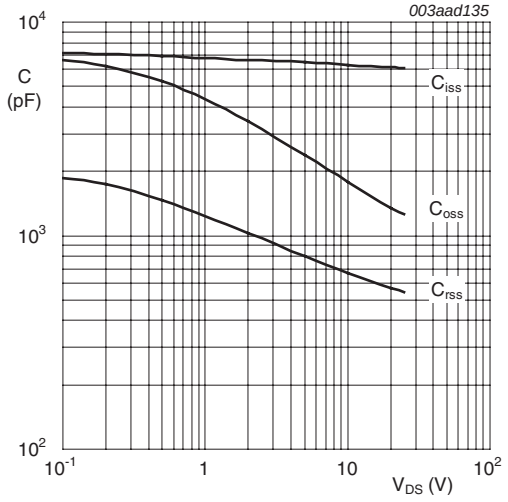


Fig 12. Gate charge waveform definitions



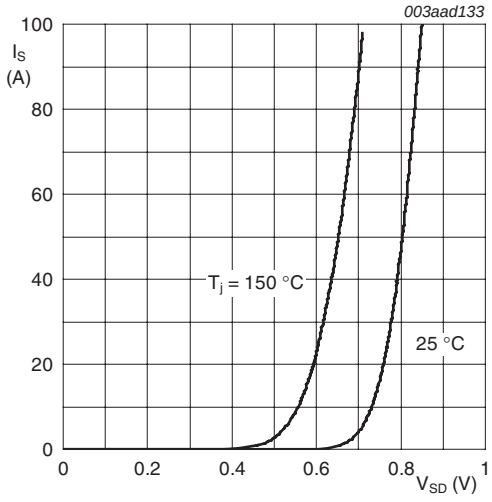
$$T_j = 25\,°C; I_D = 10\,A$$

Fig 13. Gate-source voltage as a function of gate charge; typical values



$$V_{GS} = 0\,V; f = 1\,MHz$$

Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

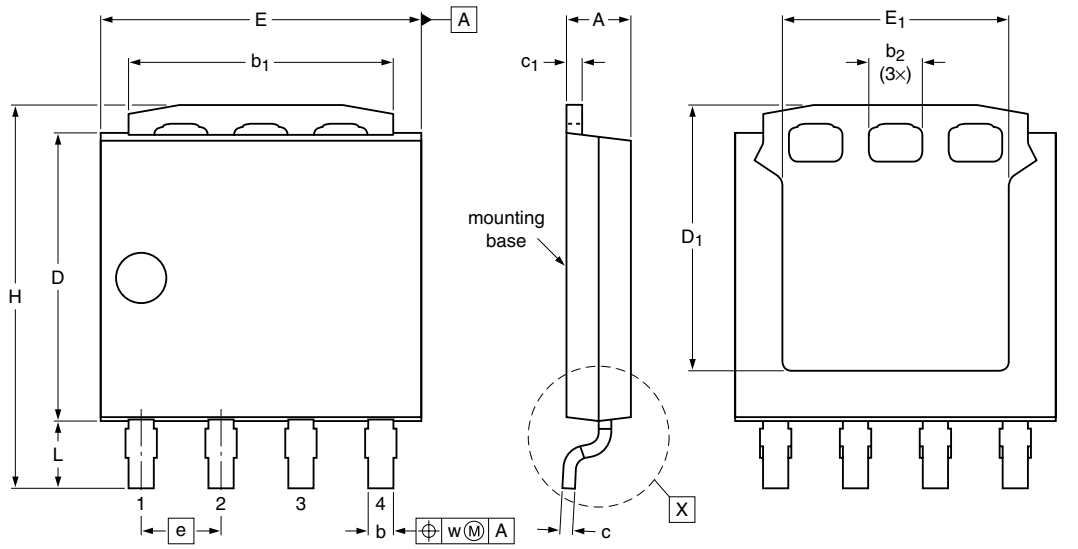


$V_{GS} = 0\,V$

Fig 15. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (LFPAK2); 4 leads **SOT1023**



Dimensions

Unit		A	A_1	b	b_1	b_2	c	c_1	$D^{(1)}$	$D_1{}^{(1)}$	$E^{(1)}$	$E_1{}^{(1)}$	e	H	L	L_p	w	y	θ
mm	max	1.10	0.15	0.50	4.41		0.25	0.30	4.70	4.45	5.30	3.7		6.2	1.3	0.85			8°
	nom					0.85							1.27				0.25	0.1	
	min	0.95	0.00	0.35	3.62		0.19	0.24	4.45		4.95	3.5		5.9	0.8	0.40			0°

Note
1. Plastic or metal protrusions of 0.15 mm per side are not included.

sot1023_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1023						~~08-10-13~~ 09-05-26

Fig 16. Package outline SOT1023

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN1R2-25YL_1	20090625	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status [1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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11. Contents

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